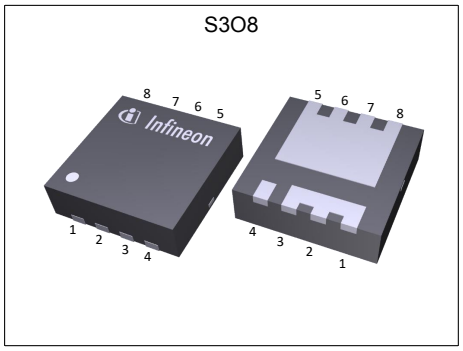
MOSFET

OptiMOS™ 5 Linear FET 2, 100 V



Features

- Ideal for soft start in Power-over-Ethernet (PoE) application
- Very low on-resistance $R_{DS(on)}$
- Wide safe operating area SOA
- N-channel, normal level
- 100% avalanche tested
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

Product validation

Fully qualified according to JEDEC for Industrial Applications

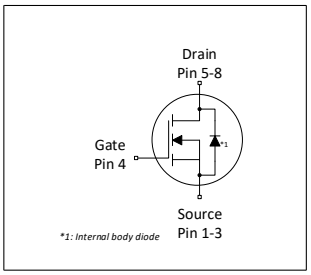


Table 1 Key Performance Parameters

Parameter	Value	Unit
V_{DS}	100	V
$R_{DS(on),max}$	11.3	mΩ
I_D	63	A
$I(V_{DS}=50\ V, t_p=10\ ms)$	2.1	A

Type / Ordering Code	Package	Marking	Related Links
ISZ113N10NM5LF2	PG-TSDSON-8	11N1LF2	-

Table of Contents

1 Maximum ratings

at T_A=25 °C, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current[1]	I_D	- - -	- - -	63 44 10	A	V_{GS}=10 V, T_C=25 °C V_{GS}=10 V, T_C=100 °C V_{GS}=10 V, T_A=25 °C, R_{thJA}=60 °C/W[2]
Pulsed drain current[3]	$I_{D,pulse}$	-	-	252	A	T_C=25 °C
Avalanche energy, single pulse[4]	E_{AS}	-	-	97	mJ	I_D=20 A, R_{GS}=25 Ω
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	- -	- -	100 2.5	W	T_C=25 °C T_A=25 °C, R_{thJA}=60 °C/W[2]
Operating and storage temperature	T_j, T_{stg}	-55	-	175	°C	-

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	1.5	°C/W	-
Thermal resistance, junction - ambient, 6 cm² cooling area[2]	R_{thJA}	-	-	60	°C/W	-

[1] Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature as specified. For other case temperatures please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.
[2] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.
[3] See Diagrams 3 and 4 for more detailed information
[4] See Diagram 14 for more detailed information

3 Electrical characteristics

at T_j=25 °C, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	100	-	-	V	V_{GS}=0 V, I_D=1 mA
Gate threshold voltage	$V_{GS(th)}$	2.3	3.1	3.9	V	V_{DS}=V_{GS}, I_D=36 µA
Zero gate voltage drain current	I_{DSS}	- -	0.1 10	1 100	µA	V_{DS}=100 V, V_{GS}=0 V, T_j=25 °C V_{DS}=100 V, V_{GS}=0 V, T_j=125 °C
Gate-source leakage current	I_{GSS}	-	10	100	nA	V_{GS}=20 V, V_{DS}=0 V
Drain-source on-state resistance	$R_{DS(on)}$	-	10.1	11.3	mΩ	V_{GS}=10 V, I_D=20 A
Gate resistance	R_G	-	1.3	1.6	Ω	-
Transconductance[1]	g_{fs}	11	22	-	S	|V_{DS}|≥2|I_D|$R_{DS(on)max}$, I_D=20 A

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance[1]	C_{iss}	-	1800	2300	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Output capacitance[1]	C_{oss}	-	260	340	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Reverse transfer capacitance[1]	C_{rss}	-	11	19	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Turn-on delay time	$t_{d(on)}$	-	8	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=20 A, $R_{G,ext}$=1.6 Ω
Rise time	t_r	-	4	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=20 A, $R_{G,ext}$=1.6 Ω
Turn-off delay time	$t_{d(off)}$	-	10	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=20 A, $R_{G,ext}$=1.6 Ω
Fall time	t_f	-	4	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=20 A, $R_{G,ext}$=1.6 Ω

Table 6 Gate charge characteristics[2]

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	12	-	nC	V_{DD}=50 V, I_D=20 A, V_{GS}=0 to 10 V
Gate charge at threshold	$Q_{g(th)}$	-	5.5	-	nC	V_{DD}=50 V, I_D=20 A, V_{GS}=0 to 10 V
Gate to drain charge[1]	Q_{gd}	-	4.4	6.6	nC	V_{DD}=50 V, I_D=20 A, V_{GS}=0 to 10 V
Switching charge	Q_{sw}	-	11	-	nC	V_{DD}=50 V, I_D=20 A, V_{GS}=0 to 10 V
Gate charge total[1]	Q_g	-	23	29	nC	V_{DD}=50 V, I_D=20 A, V_{GS}=0 to 10 V
Gate plateau voltage	$V_{plateau}$	-	6.8	-	V	V_{DD}=50 V, I_D=20 A, V_{GS}=0 to 10 V
Output charge[1]	Q_{oss}	-	30	40	nC	V_{DS}=50 V, V_{GS}=0 V

[1] Defined by design. Not subject to production test.
[2] See ″Gate charge waveforms″ for parameter definition

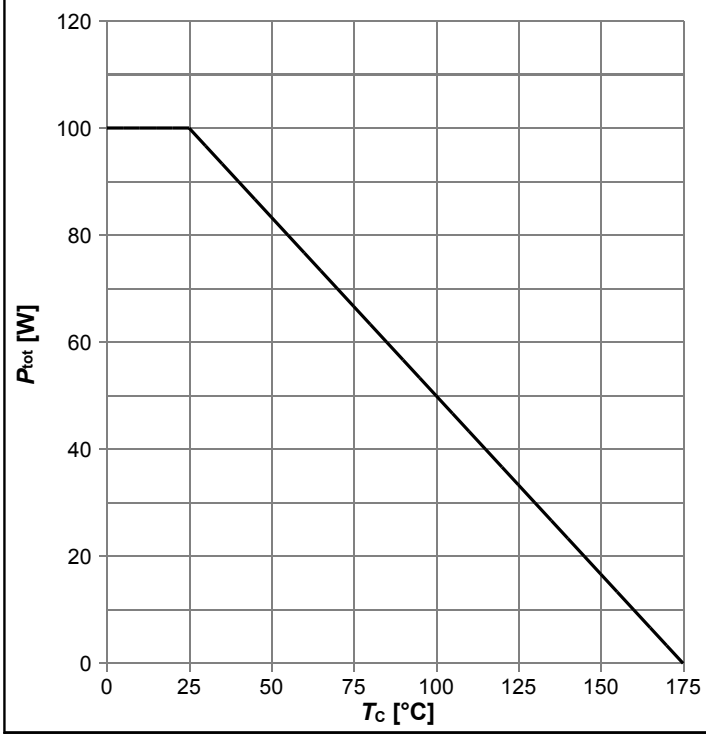
Table 7 Reverse diode

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	63	A	T_C=25 °C
Diode pulse current	$I_{S,pulse}$	-	-	252	A	T_C=25 °C
Diode forward voltage	V_{SD}	-	0.85	1.2	V	V_{GS}=0 V, I_F=20 A, T_j=25 °C
Reverse recovery time[1)]	t_{rr}	-	44	88	ns	V_R=50 V, I_F=20 A, di_F/dt=100 A/µs
Reverse recovery charge[1)]	Q_{rr}	-	54	108	nC	V_R=50 V, I_F=20 A, di_F/dt=100 A/µs

[1)] Defined by design. Not subject to production test.

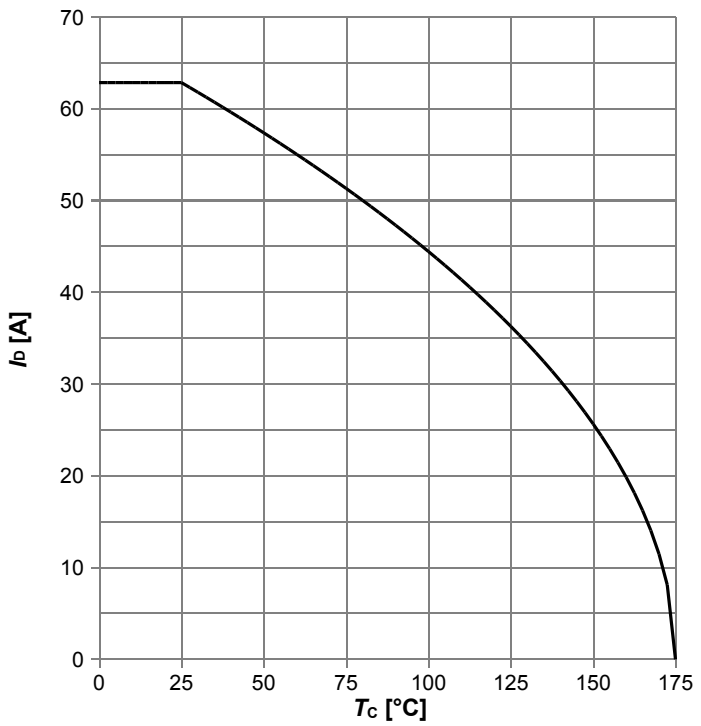
4 Electrical characteristics diagrams

Diagram 1: Power dissipation



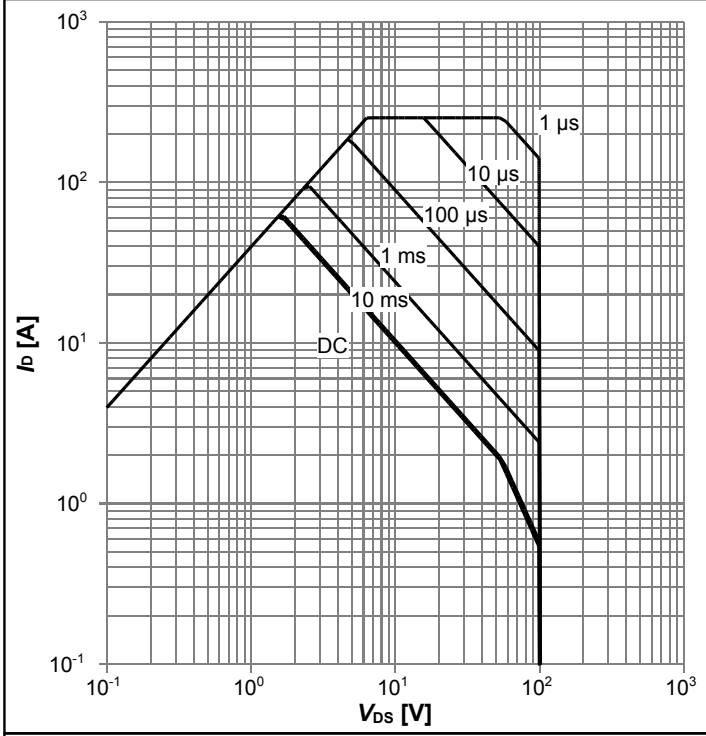
$P_{tot}=f(T_C)$

Diagram 2: Drain current



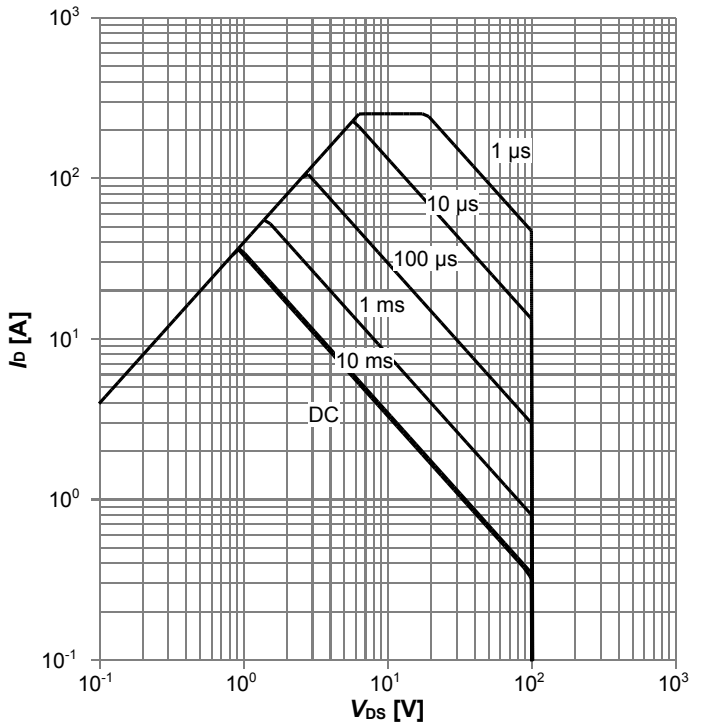
$I_D=f(T_C)$; $V_{GS}\geq 10$ V

Diagram 3: Safe operating area



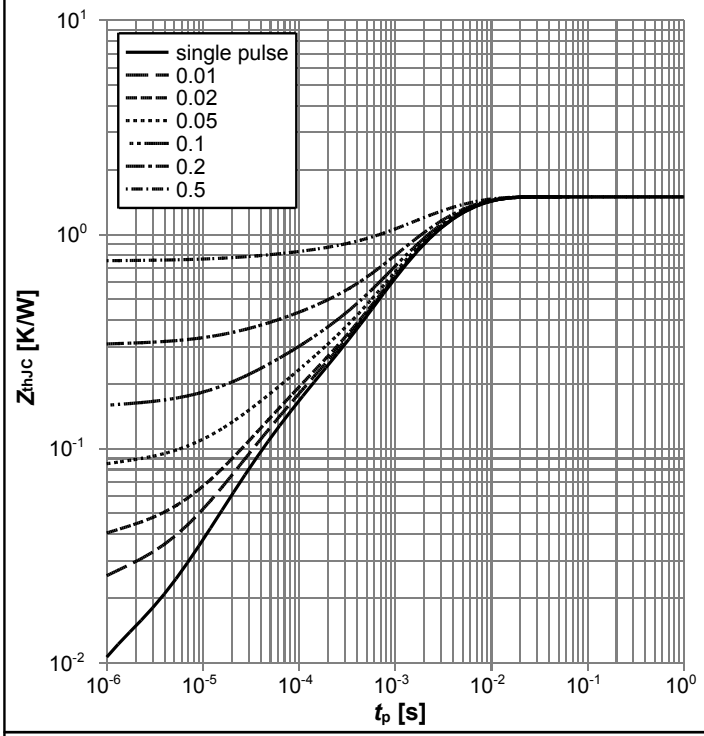
$I_D=f(V_{DS})$; $T_C=25$ °C; $D=0$; parameter: t_p

Diagram 4: Safe operating area



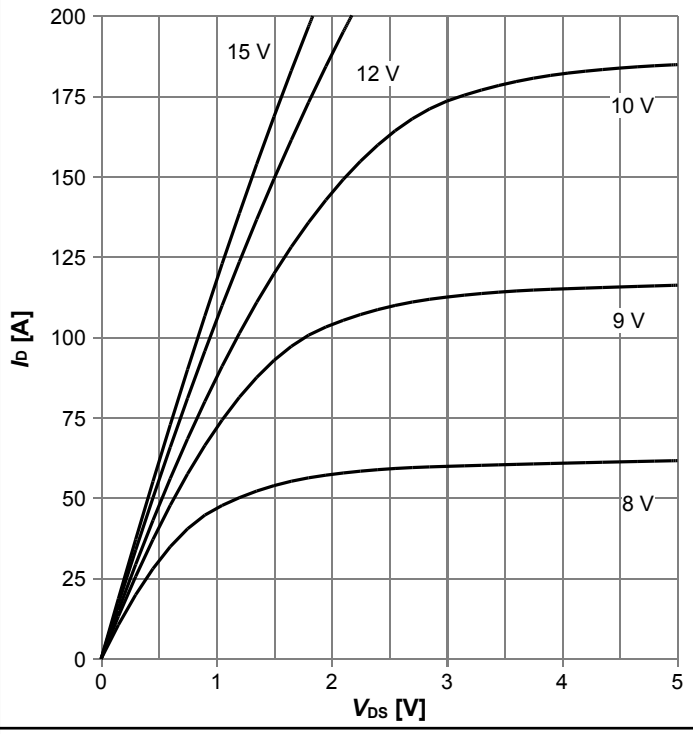
$I_D=f(V_{DS})$; $T_C=125$ °C; $D=0$; parameter: t_p

Diagram 5: Max. transient thermal impedance



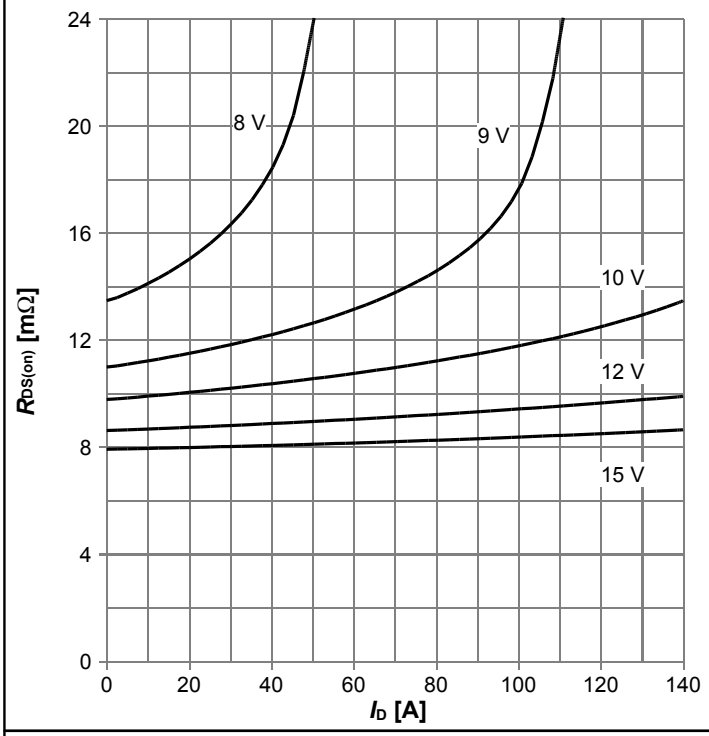
Z_{thJC}=f(t_p); parameter: D=t_p/T

Diagram 6: Typ. output characteristics



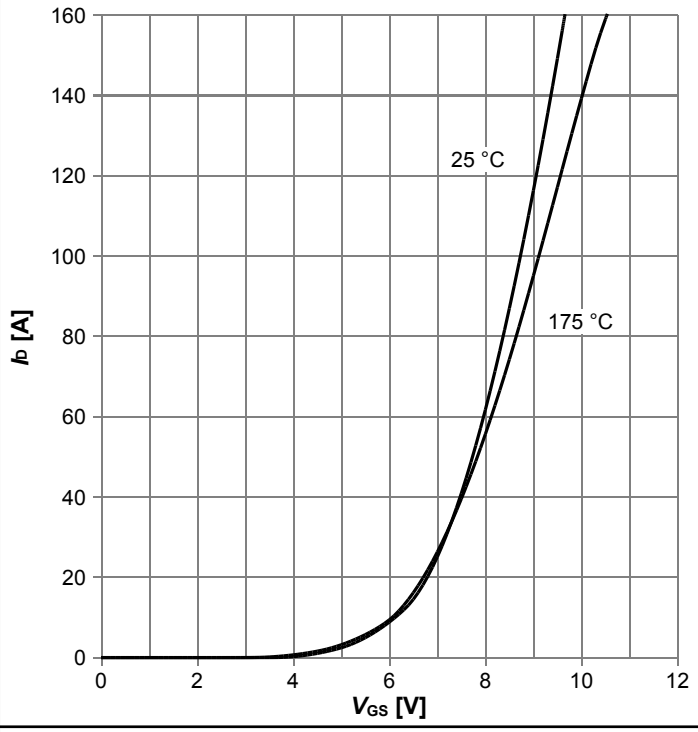
I_D=f(V_{DS}), T_j=25 °C; parameter: V_{GS}

Diagram 7: Typ. drain-source on resistance



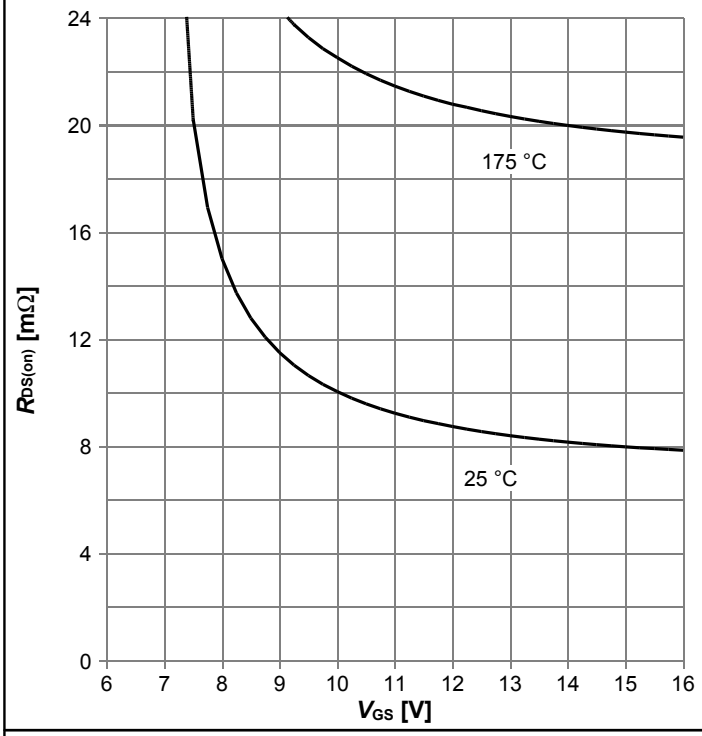
$R_{DS(on)}$=f(I_D), T_j=25 °C; parameter: V_{GS}

Diagram 8: Typ. transfer characteristics



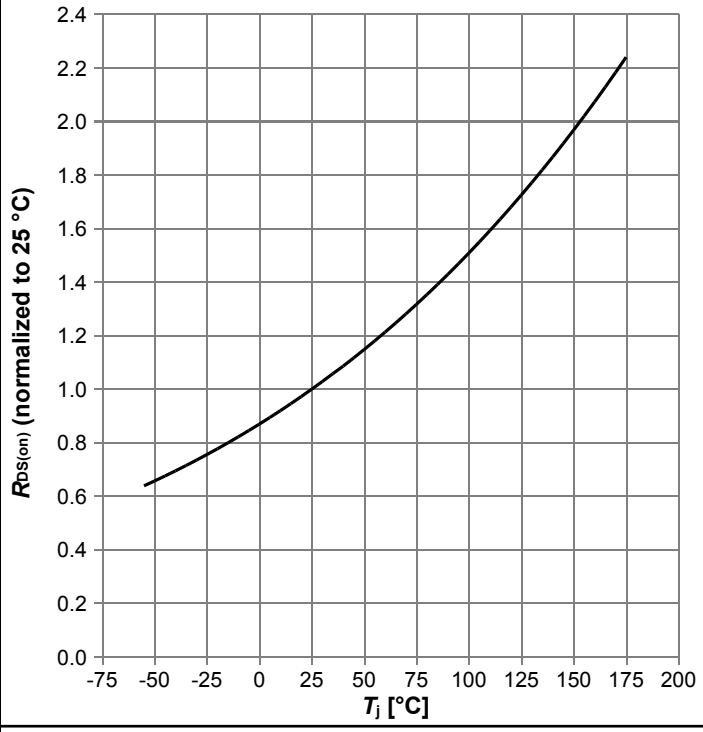
I_D=f(V_{GS}), |V_{DS}|>2|I_D|$R_{DS(on)max}$; parameter: T_j

Diagram 9: Typ. drain-source on resistance



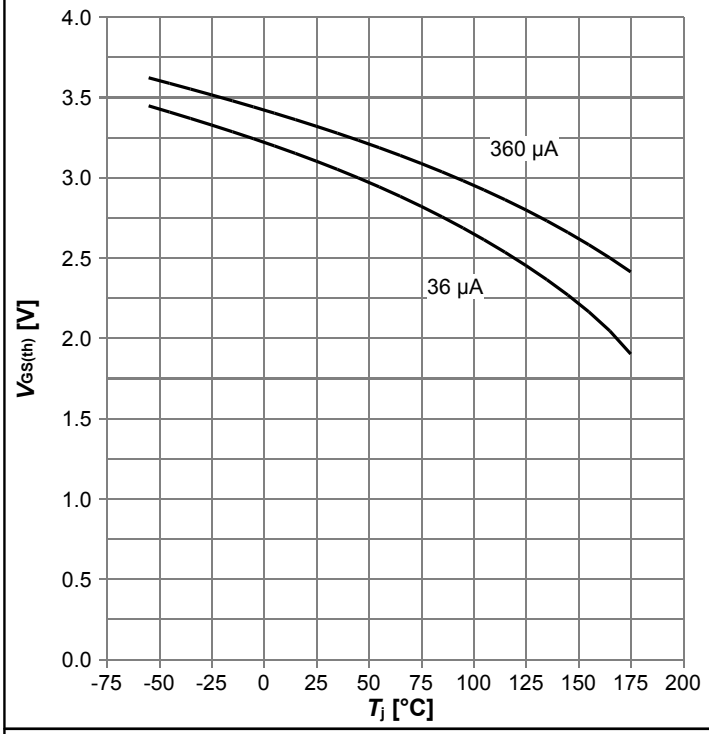
$R_{DS(on)}$=f(V_{GS}), I_D=20 A; parameter: T_j

Diagram 10: Normalized drain-source on resistance



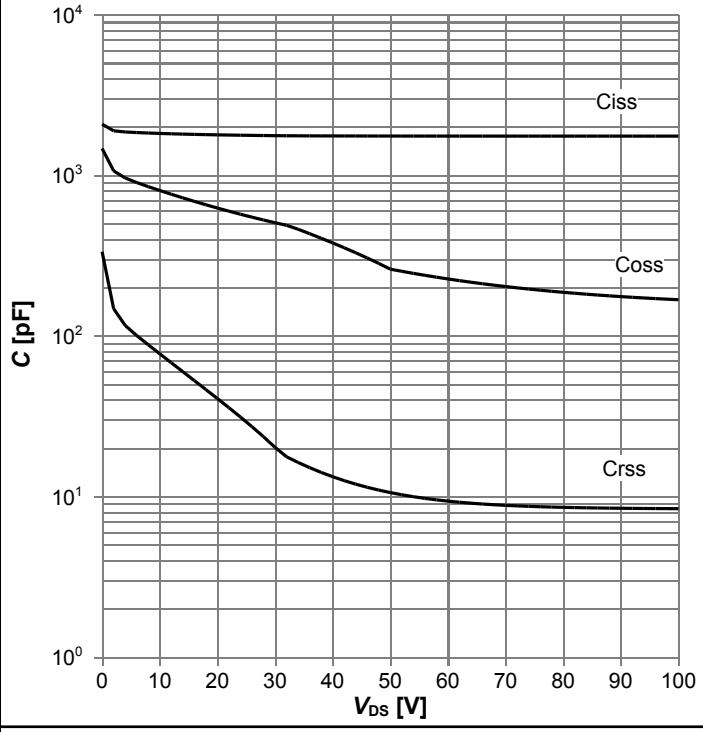
$R_{DS(on)}$=f(T_j), I_D=20 A, V_{GS}=10 V

Diagram 11: Typ. gate threshold voltage



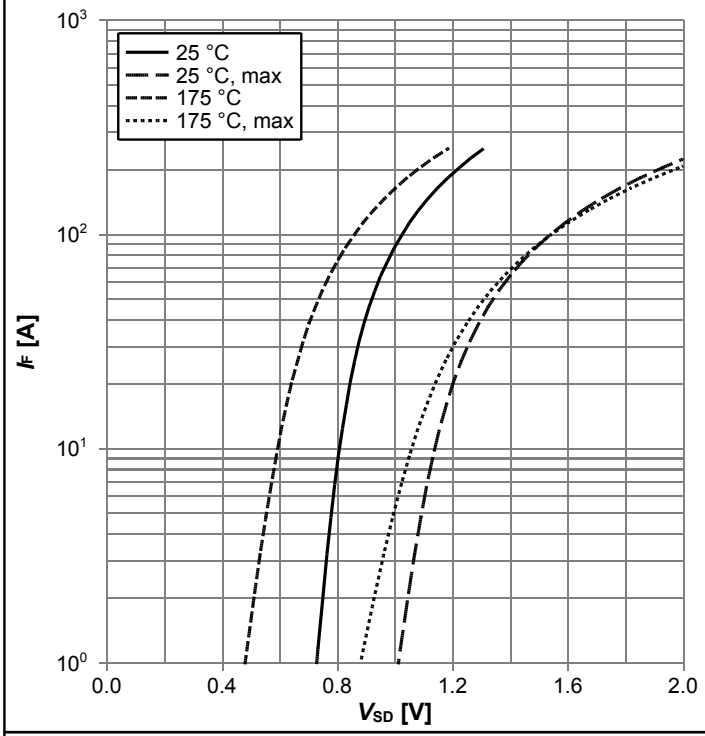
$V_{GS(th)}$=f(T_j), V_{GS}=V_{DS}; parameter: I_D

Diagram 12: Typ. capacitances



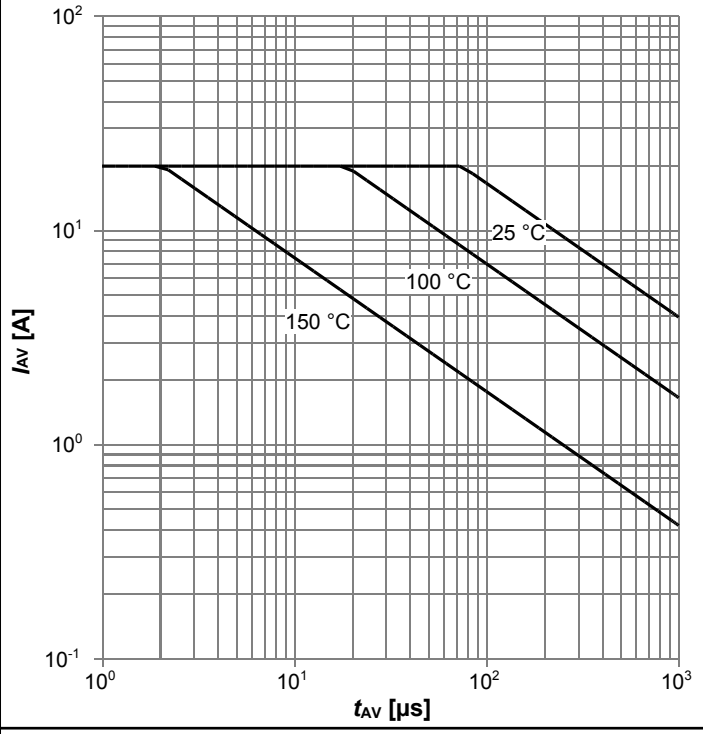
C=f(V_{DS}); V_{GS}=0 V; f=1 MHz

Diagram 13: Forward characteristics of reverse diode



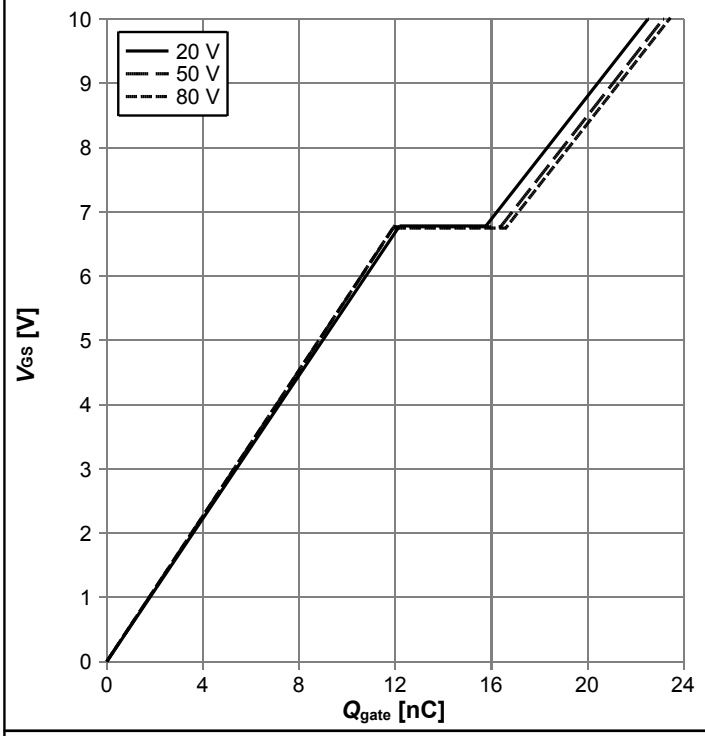
$I_F=f(V_{SD})$; parameter: T_j

Diagram 14: Avalanche characteristics



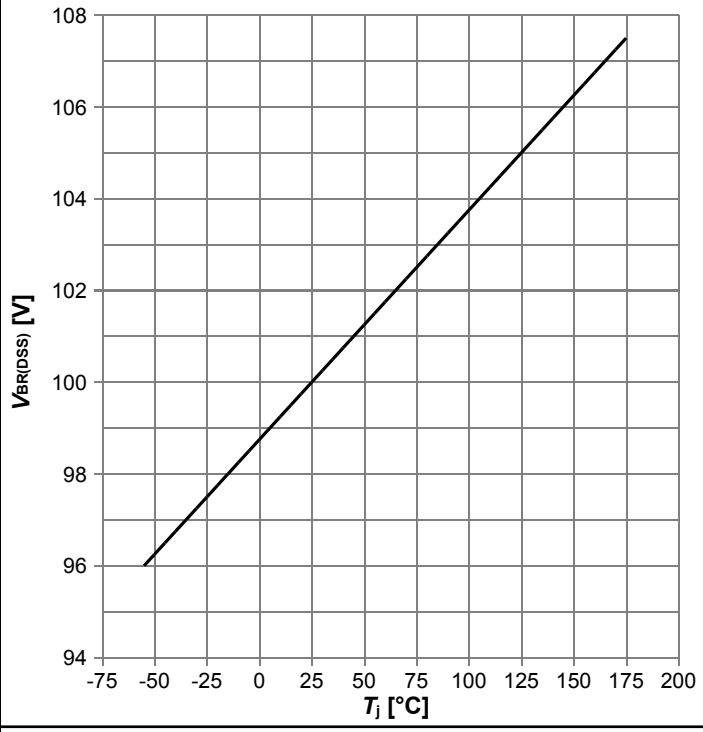
$I_{AS}=f(t_{AV})$; R_{GS}=25 Ω; parameter: $T_{j,start}$

Diagram 15: Typ. gate charge



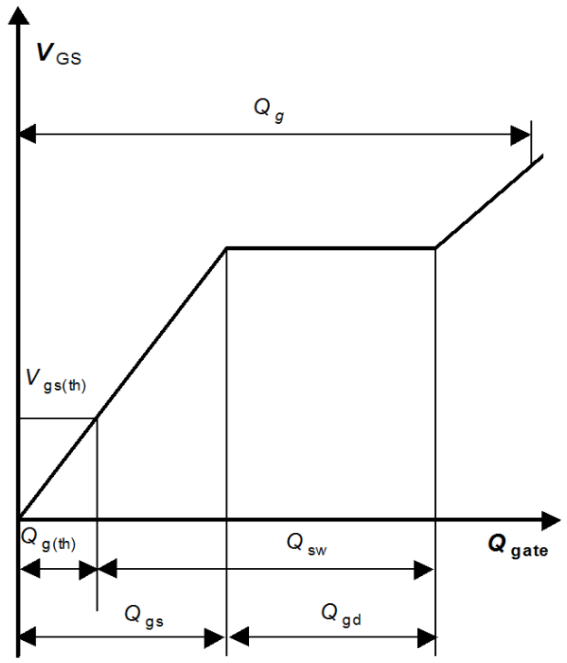
$V_{GS}=f(Q_{gate})$, I_D=20 A pulsed, T_j=25 °C; parameter: V_{DD}

Diagram 16: Drain-source breakdown voltage

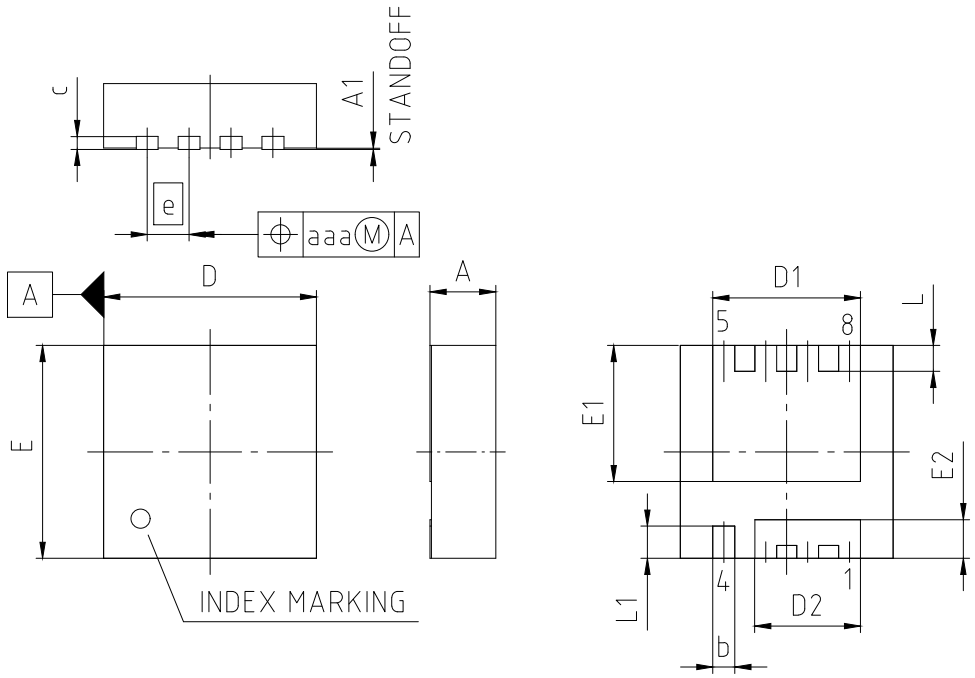


$V_{BR(DSS)}=f(T_j)$; I_D=1 mA

Diagram Gate charge waveforms



5 Package Outlines



PACKAGE - GROUP NUMBER:	PG-TSDSON-8-U03	
DIMENSIONS	**MILLIMETERS**	
	MIN.	MAX.
A	0.90	1.10
A1	0	0.05
b	0.24	0.44
c	0.10	0.30
D	3.20	3.40
D1	2.19	2.39
D2	1.54	1.74
E	3.20	3.40
E1	2.01	2.21
E2	0.50	0.70
e	0.65	
L	0.30	0.50
L1	0.40	0.60
aaa	0.06	
N	8	

NOTE:
DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS

Figure 1 Outline PG-TSDSON-8, dimensions in mm/inches

Revision History

ISZ113N10NM5LF2

Revision: 2023-11-14, Rev. 2.1

Previous Revision		
Revision	Date	Subjects (major changes since last revision)
2.1	2023-11-14	Update sales name and marking

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